PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6871137

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HOJIN KIM	08/17/2021
STEPHEN MANCINI	08/17/2021
SOO DOO CHAE	08/17/2021

RECEIVING PARTY DATA

Name:	TOKYO ELECTRON LIMITED
Street Address:	3-1 AKASAKA 5-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
Postal Code:	107-6325

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17405265

CORRESPONDENCE DATA

Fax Number: (972)732-9218

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: SLATER MATSIL, LLP
Address Line 1: 17950 PRESTON ROAD
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Address Line 4: DALLAS, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TEL-191151US02
NAME OF SUBMITTER:	SHANNON TROTTER
SIGNATURE:	/Shannon Trotter/
DATE SIGNED:	08/18/2021
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 4
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Atty. Docket No. TEL-191151US02

DECLARATION (37 CFR 1.63) AND ASSIGNMENT FOR NONPROVISIONAL UTILITY OR DESIGN PATENT APPLICATION

Title of Invention: STRESS RELIEF IN SEMICONDUCTOR WAFERS

As a below named inventor, I hereby declare that:

This declaration and assignment is directed to:

☒ The attached application having a docket number and title identified above, or
☐ United States application number or PCT international application number ____________ filed on ____________.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Assignor(s): The Assignor(s) is/are the undersigned inventor(s). The inventor(s) named below has/have made certain inventions, improvements, and/or discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application.

Assignee: The Assignee is **Tokyo Electron Limited**, a corporation of Japan having a place of business at 3-1 Akasaka 5-chome Minato-ku, Tokyo 107-6325, Japan, (herein referred to as the "ASSIGNEE"). The term "ASSIGNEE" used herein includes successors, legal representatives, and assigns of the ASSIGNEE. The ASSIGNEE desires to acquire the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents obtained from the Invention.

As an undersigned inventor, I hereby assign to the ASSIGNEE my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefrom in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, granted for the invention, to the ASSIGNEE, and I authorize and request foreign patent authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE. The entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made. I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, for the ASSIGNEE, whenever requested by the ASSIGNEE.

As an undersigned inventor, I acknowledge prior and ongoing obligations to sell, assign, and/or transfer my rights in the Invention to the ASSIGNEE. I have not sold, assigned, or otherwise transferred my rights in the Invention to another, and I am under no obligation to sell, assign, or otherwise transfer my rights in the Invention to another. I also hereby grant the ASSIGNEE, the right to insert in this Declaration and

Assignment any further identification (including, but not limited to, patent application number and filing date) which may be necessary or desirable for recording this Declaration and Assignment.

(1) Legal name of Inventor: Hojin Kim
Inventor's Signature: Date: 8/17/21
Residence City/State/Country:
Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South 255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
Citizenship: South Korea

(2) Legal name of Inventor: Stephen Mancini
Inventor's Signature: Date:
Residence City/State/Country:
Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South 255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
Citizenship:

(3) Legal name of Inventor: Soo Doo Chae
Inventor's Signature: Date: 8/17/21
Residence City/State/Country: Cohoes, NY United States
Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South 255 Fuller Rd., Suite 214, Albany, NY, 12203United States
Citizenship: South Korea

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As an undersigned inventor, I hereby assign to the ASSIGNEE my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefrom in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, granted for the invention, to the ASSIGNEE, and I authorize and request foreign patent authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE. The entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made. I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, for the ASSIGNEE, whenever requested by the ASSIGNEE.

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(1) Legal name of Inventor: Hojin Kim
Inventor's Signature: Date:
Residence City/State/Country:
Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South 255 Fuller Rd., Suite 214, Albany, NY, 12203 United States
Citizenship:

(2) Legal name of Inventor: Stephen Mancini
Inventor's Signature: Stephen A M Date: 08/17/2021
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Citizenship: United States of America

(3) Legal name of Inventor: Soo Doo Chae
Inventor's Signature: Date:
Residence City/State/Country: Cohoes, NY United States
Mailing Address: c/o TEL Technology Center, America, LLC, NanoFab 300 South 255 Fuller Rd., Suite 214, Albany, NY, 12203United States
Citizenship: